

Title (en)
TRANSPARENT SUBSTRATE COATED WITH A SILVER DEPOSIT

Title (de)
DURCHSICHTIGES SUBSTRAT MIT SILBERBESCHICHTUNG

Title (fr)
SUBSTRAT TRANSPARENT REVETU D'UNE COUCHE D'ARGENT

Publication
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Application
EP 99924598 A 19990604

Priority
• EP 99924598 A 19990604
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• EP 98110439 A 19980608

Abstract (en)
[origin: EP0963960A1] The substrate has at least one coating of silver or its alloy. Each metallic coating is in contact with two transparent, non-absorbing dielectric layers. The coated substrate is intended to be subjected to thermal tempering or bending treatment. Each of the dielectric layers have an underlayer based on a suboxide of an alloy of two metals. The above suboxide of the alloy is based on Ni and Cr. At least one metal layer is in contact with a subjacent sublayer of a metal oxide selected from Ti, Ta, Nb and Sn. The underlayer based on the suboxide of the alloy is the nearest to the substrate is in contact with a subjacent underlayer of titanium oxide. The dielectric layer between the substrate and the first metal layer comprises underlayers of oxides of metals or of alloys of metals. At least one dielectric layer has an underlayer based on a nitride of silicon and/or aluminum. Each metal layer is comprises an alloy of silver and platinum or palladium. The optical thickness of the dielectric layer nearest to the substrate is 50-90 nm, that of the other dielectric layer is 70-110 nm, that of the underlayers based on the suboxide of the alloy is 3-24 nm, and the geometric thickness of the metal layer is 8-15 nm. After thermal treatment the substrate has warping degree less than 0.3% and emissivity less than 0.08, preferably less than 0.05. Independent claims are given for: a multiple glazing unit; laminated glass; a vehicle windscreen; and a process for manufacture of the substrate, involving cathodic sputtering of the layers of the coating in an oxidizing atmosphere, preferably containing 3-7% oxygen.

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Cited by
CN102326274A; EP1829835A1; WO2005115747A1; US7597962B2; WO2010094775A1; US8409717B2; US8808864B2; US8945714B2; US9297197B2; US9403345B2; US9816316B2

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